



ALPHA & OMEGA
SEMICONDUCTOR

AON5820

20V Common-Drain Dual N-Channel MOSFET

General Description

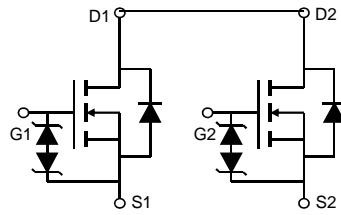
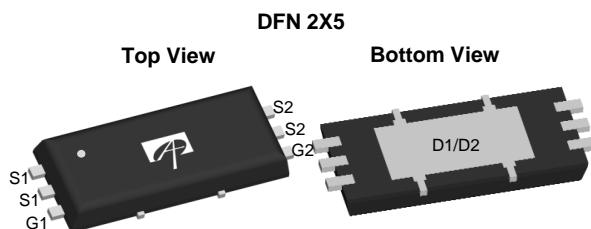
The AON5820 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V while retaining a 12V $V_{GS(MAX)}$ rating. It is ESD protected. This device is suitable for use as a uni-directional or bi-directional load switch, facilitated by its common-drain configuration.

Product Summary

V_{DS}	20V
I_D (at $V_{GS}=4.5V$)	10A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 9.5mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.0V$)	< 10mΩ
$R_{DS(ON)}$ (at $V_{GS}=3.5V$)	< 10.5mΩ
$R_{DS(ON)}$ (at $V_{GS}=3.1V$)	< 11.5mΩ
$R_{DS(ON)}$ (at $V_{GS}=2.5V$)	< 13mΩ

Typical ESD protection

HBM Class 2



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	10	A
Current $T_A=70^\circ\text{C}$		8	
Pulsed Drain Current ^C	I_{DM}	85	
Power Dissipation ^A	P_{DSM}	1.7	W
$T_A=70^\circ\text{C}$		1	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10\text{s}$	$R_{\theta JA}$	30	40	°C/W
Maximum Junction-to-Ambient ^{A,D} Steady-State		61	75	°C/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	4.5	5.5

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 10\text{V}$			10	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.3	0.65	1.0	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=4.5\text{V}, V_{DS}=5\text{V}$	85			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=10\text{A}$ $T_J=125^\circ\text{C}$	5.5 8	7.4 11	9.5 14	$\text{m}\Omega$
		$V_{GS}=4.0\text{V}, I_D=10\text{A}$	5.8	7.6	10	$\text{m}\Omega$
		$V_{GS}=3.5\text{V}, I_D=9\text{A}$	6	8	10.5	$\text{m}\Omega$
		$V_{GS}=3.1\text{V}, I_D=9\text{A}$	6.3	8.3	11.5	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}, I_D=8\text{A}$	6.8	9.2	13	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=10\text{A}$		65		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.58	1	V
I_S	Maximum Body-Diode Continuous Current				2.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$	1000	1255	1510	pF
C_{oss}	Output Capacitance		150	220	290	pF
C_{rss}	Reverse Transfer Capacitance		100	168	235	pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		2.5		$\text{K}\Omega$
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=10\text{A}$	10	12.5	15	nC
Q_{gs}	Gate Source Charge			5.5		nC
Q_{gd}	Gate Drain Charge			6.5		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, R_L=1\Omega, R_{\text{GEN}}=3\Omega$		1.1		μs
t_r	Turn-On Rise Time			2.6		μs
$t_{\text{D(off)}}$	Turn-Off Delay Time			7		μs
t_f	Turn-Off Fall Time			7.4		μs
t_{rr}	Body Diode Reverse Recovery Time	$I_F=10\text{A}, dI/dt=500\text{A}/\mu\text{s}$	8.5	11	13.5	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=10\text{A}, dI/dt=500\text{A}/\mu\text{s}$	12	15	18	nC

A. The value of R_{QJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation P_{DSM} is based on R_{QJA} and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

D. The R_{QJA} is the sum of the thermal impedance from junction to case R_{QJC} and case to ambient.

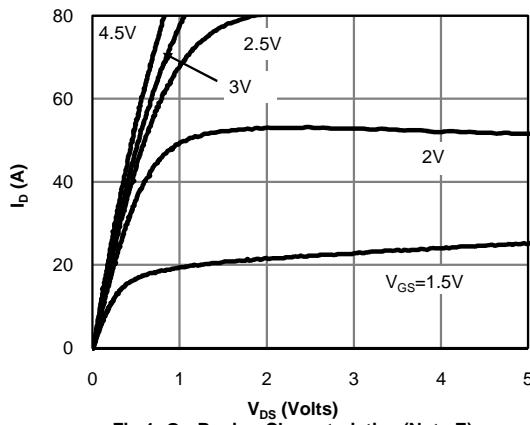
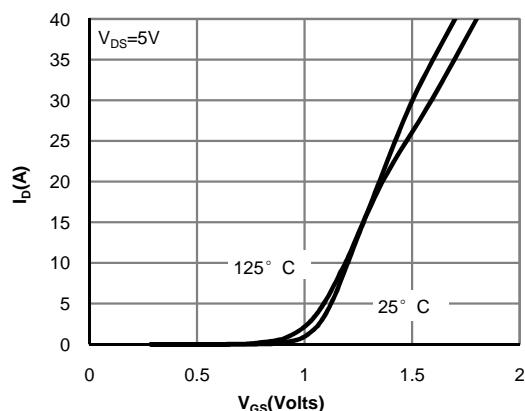
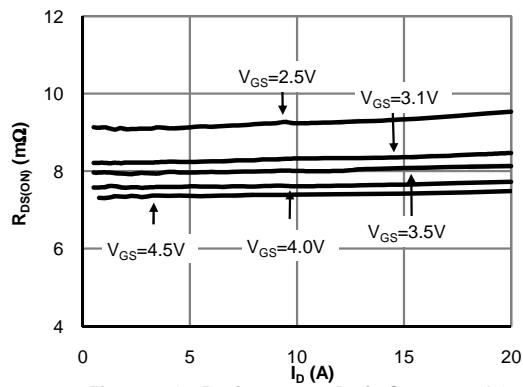
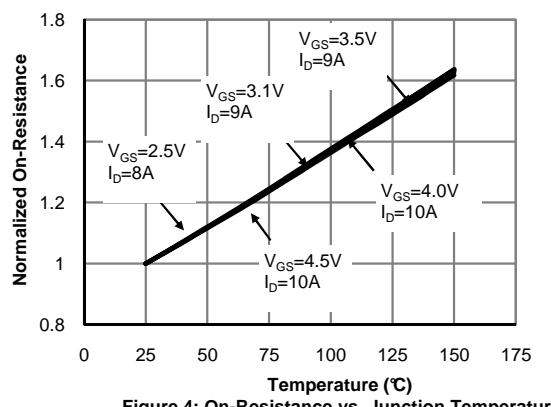
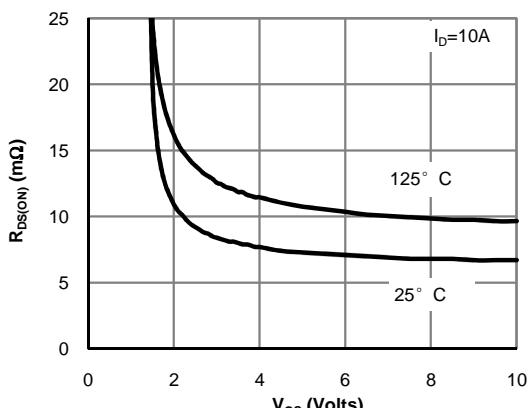
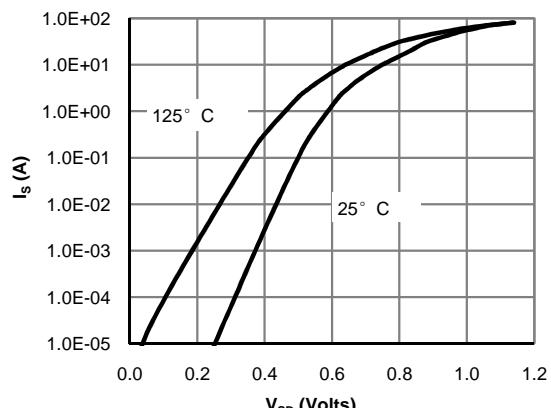
E. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

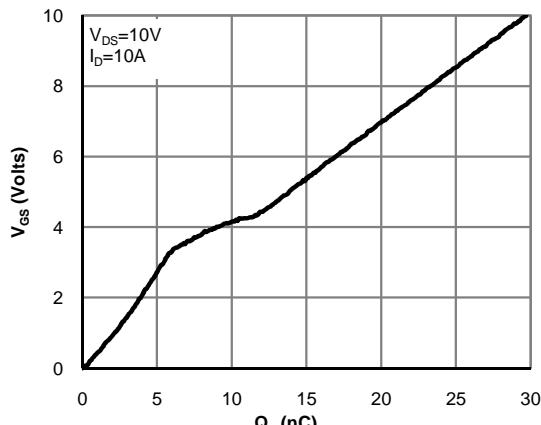
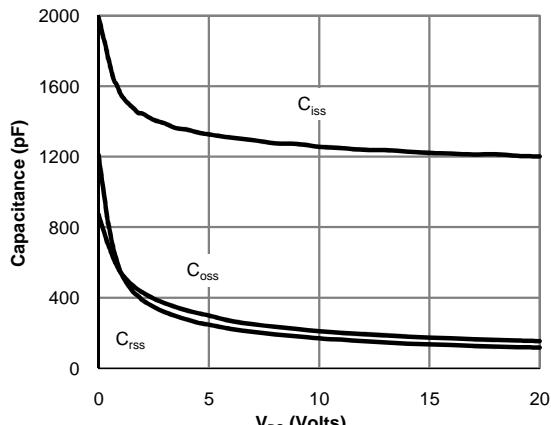
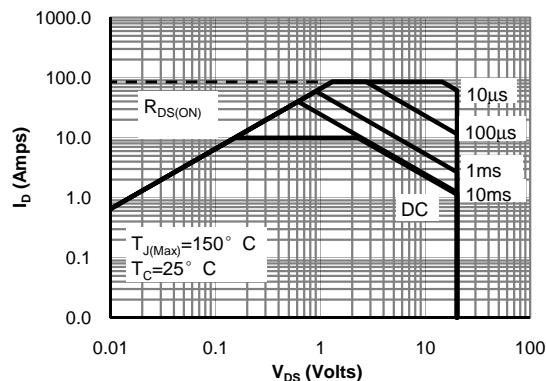
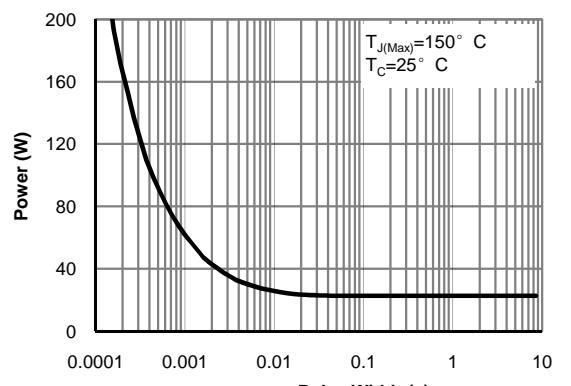
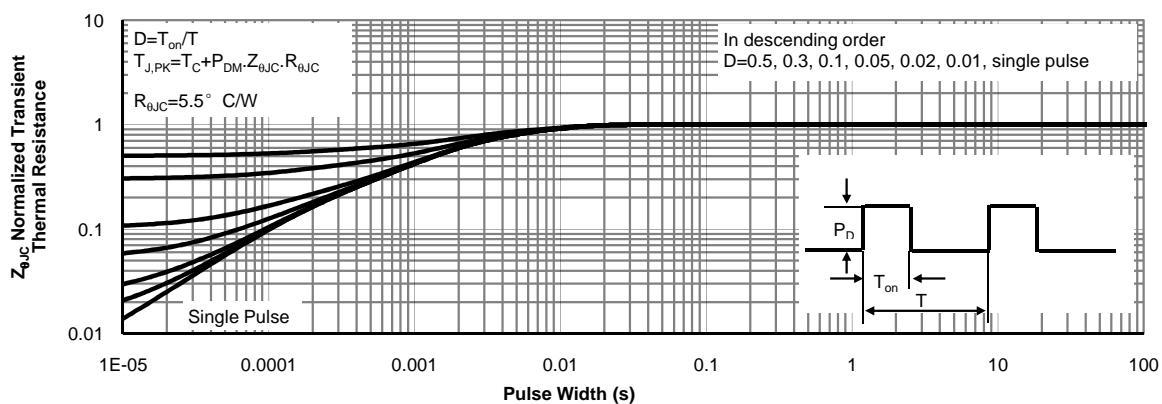
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

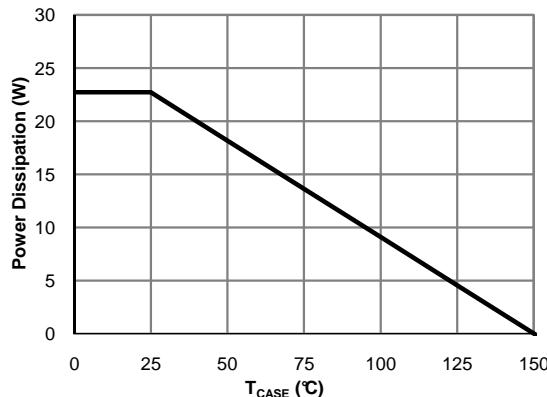
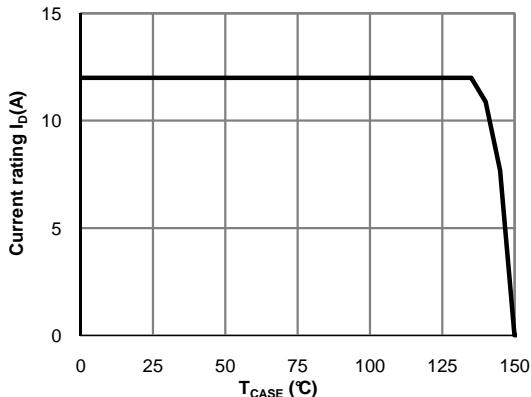
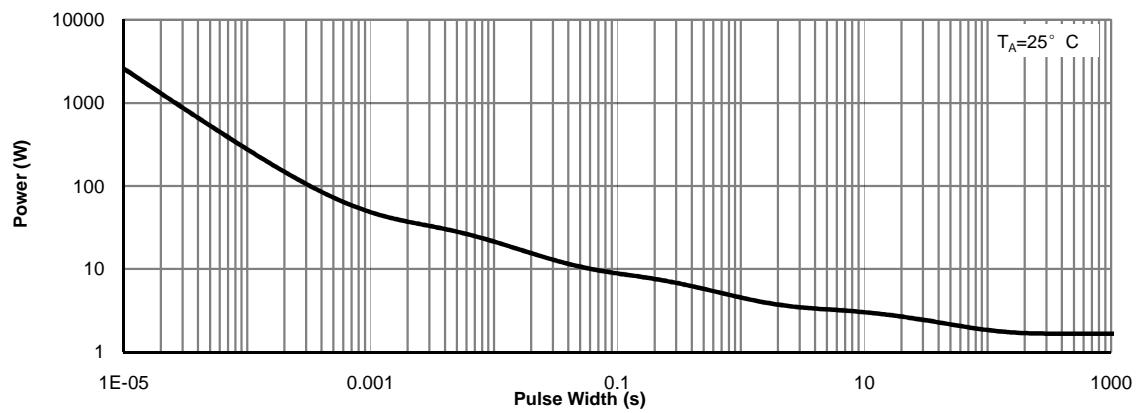
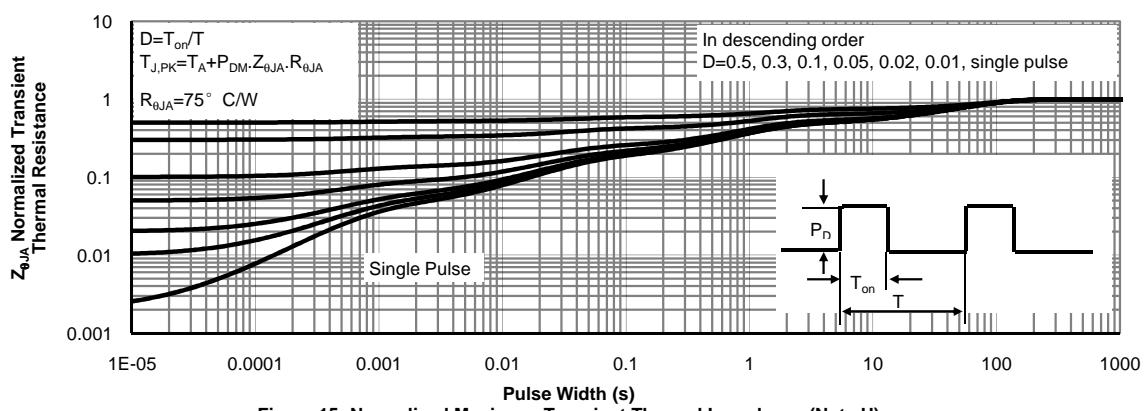
G. The maximum current rating is package limited.

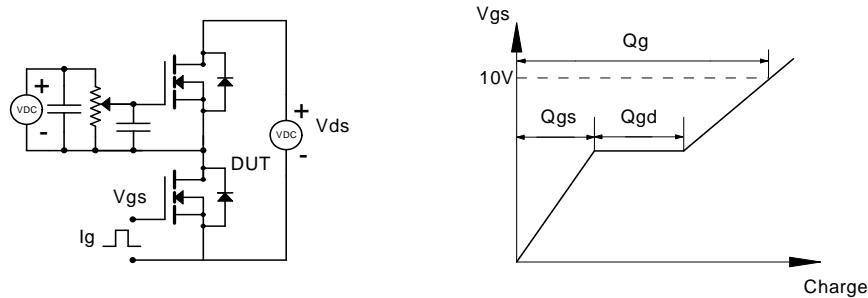
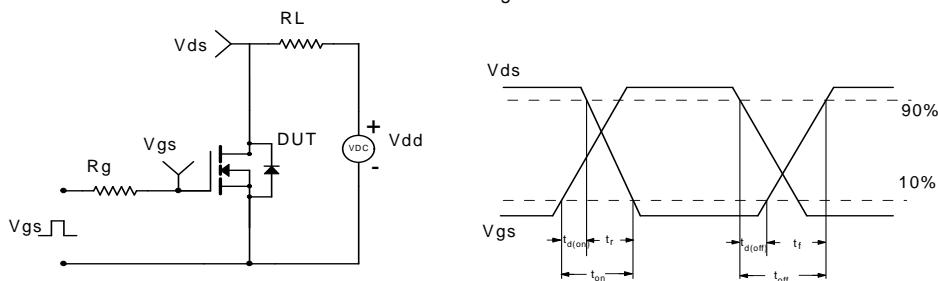
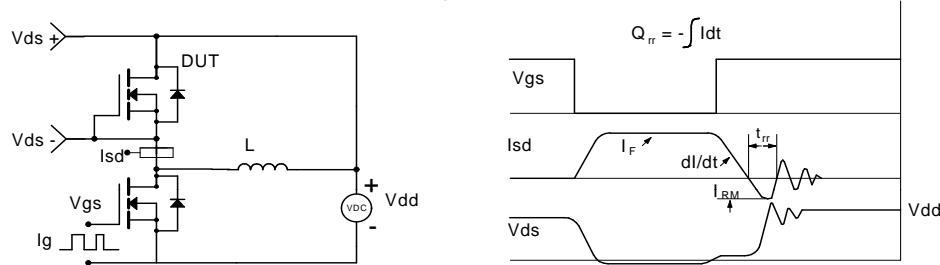
H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Cooling-Area (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 12: Power De-rating (Note F)

Figure 13: Current De-rating (Note F)

Figure 14: Single Pulse Power Rating Junction-to-Ambient (Note H)

Figure 15: Normalized Maximum Transient Thermal Impedance (Note H)


Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

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